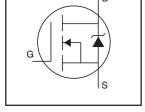
# International TOR Rectifier

# **AUTOMOTIVE GRADE**

# **AUIRFZ44N**

### **Features**

- Advanced Planar Technology
- Low On-Resistance
- Dynamic dV/dT Rating
- 175°C Operating Temperature
- Fast Switching
- Fully Avalanche Rated
- Repetitive Avalanche Allowed up to Tjmax
- Lead-Free, RoHS Compliant
- Automotive Qualified \*



# 

# Description

Specifically designed for Automotive applications, this Stripe Planar design of HEXFET® Power MOSFETs utilizes the latest processing techniques to achieve low on-resistance per silicon area. This benefit combined with the fast switching speed and ruggedized device design that HEXFET power MOSFETs are well known for, provides the designer with an extremely efficient and reliable device for use in Automotive and a wide variety of other applications.



G	D	S
Gate	Drain	Source

# **Absolute Maximum Ratings**

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only; and functional operation of the device at these or any other condition beyond those indicated in the specifications is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions. Ambient temperature  $(T_A)$  is  $25^{\circ}$ C, unless otherwise specified.

	Parameter	Max.	Units	
I <sub>D</sub> @ T <sub>C</sub> = 25°C	Continuous Drain Current, V <sub>GS</sub> @ 10V	49		
I <sub>D</sub> @ T <sub>C</sub> = 100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V	35	Α	
I <sub>DM</sub>	Pulsed Drain Current ①	160	$\neg$	
P <sub>D</sub> @T <sub>C</sub> = 25°C	Power Dissipation	94	W	
	Linear Derating Factor	0.63	W/°C	
V <sub>GS</sub>	Gate-to-Source Voltage	±20	V	
E <sub>AS</sub> (Thermally Limited)	Single Pulse Avalanche Energy ©	150	1	
E <sub>AS</sub> (tested)	Single Pulse Avalanche Energy Tested Value ®	530	mJ mJ	
I <sub>AR</sub>	Avalanche Current ①	25	А	
E <sub>AR</sub>	Repetitive Avalanche Energy ①	9.4	mJ	
dv/dt	Peak Diode Recovery dv/dt 3	5.0	V/ns	
TJ	Operating Junction and	-55 to + 175		
T <sub>STG</sub>	Storage Temperature Range		°C	
	Soldering Temperature, for 10 seconds	300 (1.6mm from case )		
	Mounting Torque, 6-32 or M3 screw	10 lbf•in (1.1N•m)		

# **Thermal Resistance**

	Parameter	Тур.	Max.	Units
$R_{ heta JC}$	Junction-to-Case		1.5	
$R_{\theta CS}$	Case-to-Sink, Flat, Greased Surface	0.50		°C/W
$R_{\theta JA}$	Junction-to-Ambient		62	

HEXFET® is a registered trademark of International Rectifier.

<sup>\*</sup>Qualification standards can be found at http://www.irf.com/

# Static Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise specified)

	Parameter	Min.	Тур.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	55			V	$V_{GS} = 0V, I_D = 250\mu A$
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient		0.058		V/°C	Reference to 25°C, I <sub>D</sub> = 1mA
R <sub>DS(on)</sub>	Static Drain-to-Source On-Resistance			17.5	mΩ	V <sub>GS</sub> = 10V, I <sub>D</sub> = 25A ④
$V_{GS(th)}$	Gate Threshold Voltage	2.0		4.0	V	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$
gfs	Forward Transconductance	19			S	$V_{DS} = 25V, I_{D} = 25A \oplus$
I <sub>DSS</sub>	Drain-to-Source Leakage Current			25	μΑ	$V_{DS} = 55V, V_{GS} = 0V$
				250		$V_{DS} = 44V, V_{GS} = 0V, T_{J} = 150^{\circ}C$
I <sub>GSS</sub>	Gate-to-Source Forward Leakage			100	nA	$V_{GS} = 20V$
	Gate-to-Source Reverse Leakage			-100		V <sub>GS</sub> = -20V

# Dynamic Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise specified)

$Q_g$	Total Gate Charge	T		63		I <sub>D</sub> = 25A
$Q_{gs}$	Gate-to-Source Charge			14	nC	$V_{DS} = 44V$
$Q_{gd}$	Gate-to-Drain ("Miller") Charge	_	_	23		V <sub>GS</sub> = 10V,See Fig 6 and 13
t <sub>d(on)</sub>	Turn-On Delay Time		12			V <sub>DD</sub> = 28V
t <sub>r</sub>	Rise Time		60			I <sub>D</sub> = 25A
t <sub>d(off)</sub>	Turn-Off Delay Time		44		ns	$R_G = 12\Omega$
t <sub>f</sub>	Fall Time		45			V <sub>GS</sub> = 10V, See Fig.10 ④
L <sub>D</sub>	Internal Drain Inductance		4.5		nH	Between lead, 6mm (0.25in.)
L <sub>S</sub>	Internal Source Inductance	<b> </b>	7.5			from package and center of die contact
C <sub>iss</sub>	Input Capacitance		1470			V <sub>GS</sub> = 0V
Coss	Output Capacitance		360		pF	$V_{DS} = 25V$
C <sub>rss</sub>	Reverse Transfer Capacitance	T —	88			f = 1.0MHz, See Fig.5
E <sub>AS</sub>	Single Pulse Avalanche Energy ②		530 S	150©	mJ	I <sub>AS</sub> = 25A, L= 0.47mH

# **Diode Characteristics**

	Parameter	Min.	Тур.	Max.	Units	Conditions	
Is	Continuous Source Current			49		MOSFET symbol	
	(Body Diode)			49	l A	showing the	
$I_{SM}$	Pulsed Source Current			160	160	integral reverse	
	(Body Diode) ①			160		p-n junction diode.	
$V_{SD}$	Diode Forward Voltage			1.3	V	$T_J = 25^{\circ}C$ , $I_S = 25A$ , $V_{GS} = 0V$ @	
t <sub>rr</sub>	Reverse Recovery Time		63	95	ns	$T_J = 25^{\circ}C, I_F = 25A$	
Q <sub>rr</sub>	Reverse Recovery Charge		170	260	nC	di/dt = 100A/µs ④	
t <sub>on</sub>	Forward Turn-On Time	Intrinsic	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

### Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature. (See fig. 11)
- $\begin{tabular}{ll} \hline \& Starting $T_J=25^\circ$C, $L=0.48mH$\\ $R_G=25\Omega$, $I_{AS}=25A$. (See Figure 12) \\ \hline \end{tabular}$
- $\label{eq:loss_def} \begin{tabular}{ll} $I_{SD} \leq 25A, \ di/dt \leq 230A/\mu s, \ V_{DD} \leq V_{(BR)DSS}, \\ $T_J \leq 175^{\circ}C$ \end{tabular}$
- 4 Pulse width  $\leq$  400 $\mu$ s; duty cycle  $\leq$  2%.
- ⑤ This is a typical value at device destruction and represents operation outside rated limits.
- $\mbox{\ \ }$  This is a calculated value limited to  $T_J=175^{\circ}C$  .

# Qualification Information<sup>†</sup>

		Automotive				
		(per AEC-Q101) ††				
		qualification. I	This part number(s) passed Automotive R's Industrial and Consumer qualification by extension of the higher Automotive level.			
Moisture Se	ensitivity Level	3L-TO-220 N/A				
	Machine Model	Class M3(+/- 400V ) <sup>†††</sup> (per AEC-Q101-002)				
ESD Human Body Model		Class H1C(+/- 1250V ) <sup>†††</sup> (per AEC-Q101-001)				
	Charged Device Model	Class C5(+/- 1250V ) <sup>†††</sup> (per AEC-Q101-005)				
RoHS Comp	oliant	Yes				

<sup>†</sup> Qualification standards can be found at International Rectifier's web site: http://www.irf.com/

<sup>††</sup> Exceptions to AEC-Q101 requirements are noted in the qualification report.

<sup>†††</sup> Highest passing voltage

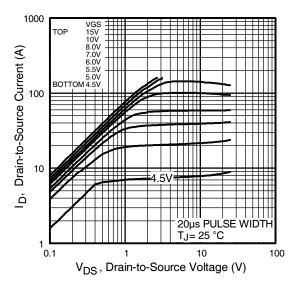


Fig 1. Typical Output Characteristics

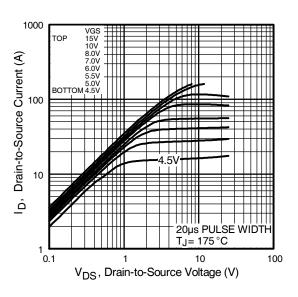


Fig 2. Typical Output Characteristics

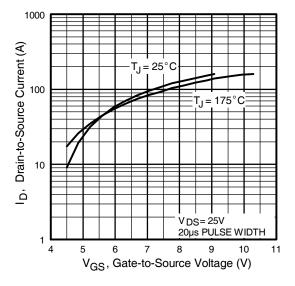
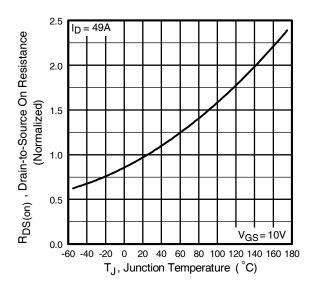
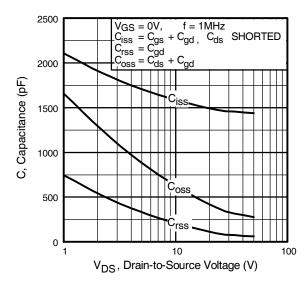


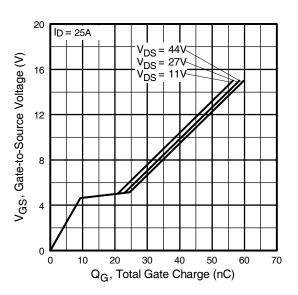
Fig 3. Typical Transfer Characteristics



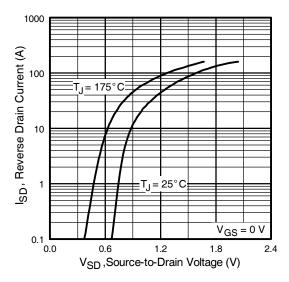
**Fig 4.** Normalized On-Resistance Vs. Temperature



**Fig 5.** Typical Capacitance Vs. Drain-to-Source Voltage



**Fig 6.** Typical Gate Charge Vs. Gate-to-Source Voltage



**Fig 7.** Typical Source-Drain Diode Forward Voltage

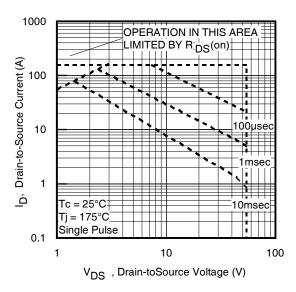
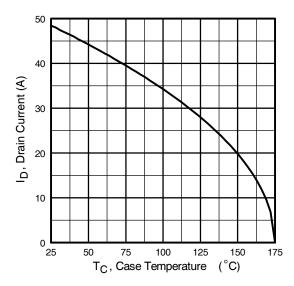


Fig 8. Maximum Safe Operating Area



**Fig 9.** Maximum Drain Current Vs. Case Temperature

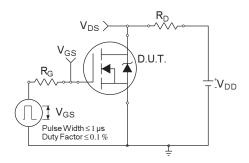


Fig 10a. Switching Time Test Circuit

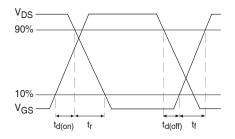


Fig 10b. Switching Time Waveforms

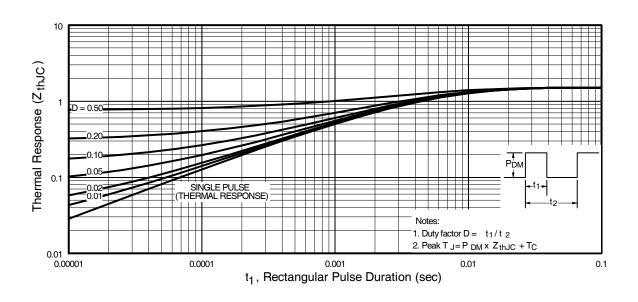


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

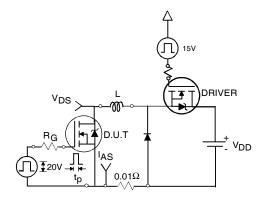


Fig 12a. Unclamped Inductive Test Circuit

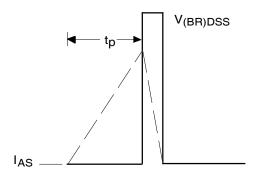


Fig 12b. Unclamped Inductive Waveforms

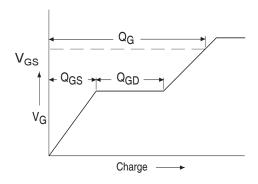


Fig 13a. Basic Gate Charge Waveform

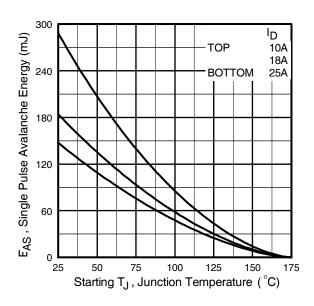


Fig 12c. Maximum Avalanche Energy Vs. Drain Current

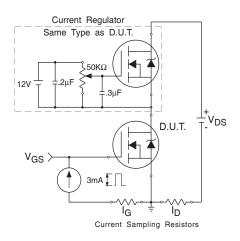
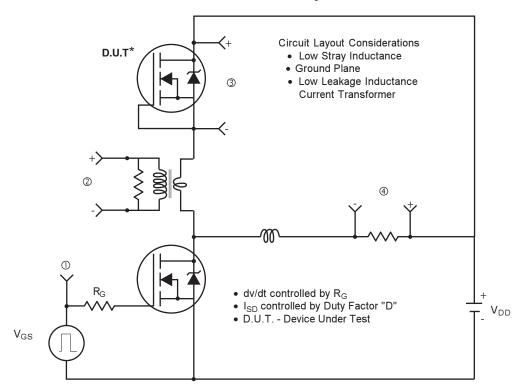
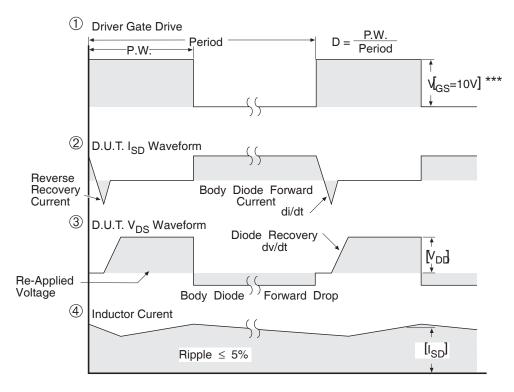


Fig 13b. Gate Charge Test Circuit

# Peak Diode Recovery dv/dt Test Circuit



<sup>\*</sup> Reverse Polarity of D.U.T for P-Channel

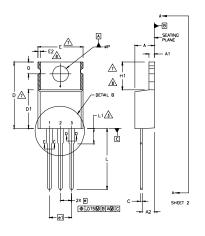


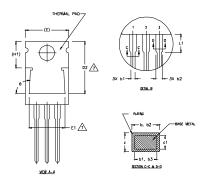
\*\*\*  $V_{GS}$  = 5.0V for Logic Level and 3V Drive Devices

Fig 14. For N-channel HEXFET® power MOSFETs

# TO-220AB Package Outline

Dimensions are shown in millimeters (inches)





#### NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5 M- 1994.

  DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS].

  LEAD DIMENSION AND FINISH UNCONTROLLED IN L1.

  DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH

  SHALL NOT EXCEED .005" (0.127) PER SIDE. THESE DIMENSIONS ARE

  MEASURED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.

DIMENSION 61 & c1 APPLY TO BASE METAL ONLY.

CONTROLLING DIMENSION: INCHES.

- THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS E,H1,D2 & E1
- DIMENSION E2 X H1 DEFINE A ZONE WHERE STAMPING AND SINGULATION IRREGULARITIES ARE ALLOWED.

SYMBOL	MILLIM	ETERS	INC	HES	
	MIN.	MAX.	MIN.	MAX.	NOTES
Α	3.56	4.82	.140	.190	
A1	0,51	1,40	.020	.055	
A2	2.04	2.92	.080	.115	
b	0.38	1.01	.015	.040	
b1	0.38	0.96	.015	.038	5
b2	1,15	1,77	.045	.070	
b3	1,15	1,73	.045	.068	
С	0.36	0.61	.014	,024	
c1	0.36	0.56	.014	.022	5
D	14.22	16,51	.560	,650	4
D1	8.38	9.02	.330	.355	
D2	12.19	12.88	.480	.507	7
E	9.66	10.66	.380	.420	4,7
E1	8.38	8.89	.330	.350	7
e		2.54 BSC 5.08		BSC	
e1	5,	J8	,200	BSC	
H1	5,85	6,55	.230	.270	7,8
L	12.70	14,73	.500	.580	
L1	-	6.35	-	.250	3
ØΡ	3.54	4.08	,139	.161	
Q	2.54	3.42	.100	.135	
ø	90*-	-93*	90'-	-93'	

#### LEAD ASSIGNMENTS

# HEXFET

# 1.- GATE 2.- DRAIN 3.- SOURCE

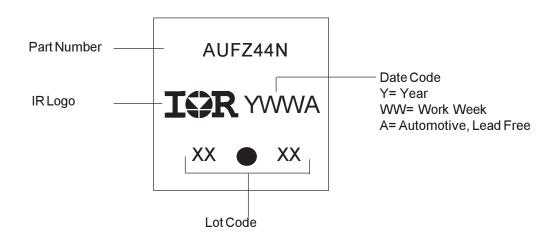
## IGBTs, CoPACK

- 1.- GATE 2.- COLLECTOR 3.- EMITTER

#### DIODES

- 1.- ANODE/OPEN 2.- CATHODE 3.- ANODE

# TO-220AB Part Marking Information



# **Ordering Information**

Base part	Package Type	Standard Pack	Complete Part Number	
		Form	Quantity	
AUIRFZ44N	TO-220	Tube	50	AUIRFZ44N

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